	PCN Number: 202		2022	20627000.1			PCN Date:		June 29, 2022	
Title: Qualification of CF			of CFA	AB as an additional Fab site options			ns for select		LBC3S devices	
Customer Contact:			PCN Manager			Dept:		Quality Services		
				Sami			ole requests			
Proposed 1 <sup>st</sup> Ship Date:			: 5	Sep 29, 2022		ccepto			July 29, 2022*	
*Sa	ample r	equests rece	ived a	fter July 29, 2	022 will not	t be su	upp	orted.		
Cha	ange Ty	pe:								
	Assembly Site			Assembly F	rocess		Assembly Materials			
	Design			Electrical S	pecification			Mech	nanical Specificatio	n
	Test Si				ipping/Labeli			Test Process		
	Wafer Bump Site			Wafer Bump Material			Wafer Bump Process			
$\square$	Wafer	Fab Site		Wafer Fab			Wafer Fab Process			
				Part numbe						
_				PCN	Details					
		n of Change:				6 it - C		<b>C</b> = 1 = 1 = 1		
				the devices liste					ation facilities as a ection.	[]
		Current Fa	ab Site	е		N	lew	Fab S	Site	
F	ab Site	Process	Wat	fer Diameter	Fab Site	Pro	oces	SS	Wafer Diameter	
	DL-LIN	LBC3S		150 mm	054.0				200	
	DL-LIN	LBC3S		200 mm	CFAB	LBC3S		>	200 mm	
Reason for Change:These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):										
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Texas Instruments Incorporated

TI Information - Selective Disclosure

PCN# 20220627000.1

MAX3238ECPWR	TLC2254CPW	TLV2254AIPW	TLV2375IPWR
MAX3238IPWR	TLC2254CPWR	TLV2254AIPWR	TLV2474AIPWR
SN1003028DBVR	TLC2254IN	TLV2264AIPWR	TLV271IDBVR
TLC072CDGN	TLC2264AIPWR	TLV2371IDBVR	TLV271IDBVT
TLC072CDGNR	TLC2264CN	TLV2371IDBVT	TLV272CDGK
TLC072CP	TLC2264CPWR	TLV2372IDGK	TLV272CDGKR
TLC072IDGN	TLC2264IN	TLV2372IDGKR	TLV272IDGK
TLC072IDGNR	TLC2274ACN	TLV2372IP	TLV272IDGKR
TLC073CDGQ	TLC2274ACPWR	TLV2373IDGS	TLV272IP
TLC073IDGQ	TLC2274AIPW	TLV2373IDGSR	TLV274CPWR
TLC073IDGQR	TLC2274AIPWR	TLV2374IN	TLV274IN
TLC082CDGN	TLC2274CN	TLV2374IPW	TLV274IPW
TLC082CDGNR	TLC2274CNSR	TLV2374IPWR	TLV274IPWR
TLC082IDGN	TLC2274CPWR	TLV2375ID	TRS3238EIPWR
TLC082IDGNR	TLC2274IPW	TLV2375IDR	

# **Qualification Report**

# Approve Date 23-May-2022

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TLC2264AQPWRQ1	QBS Process Reference: CD3301RHHR	QBS Package Reference: TLV9064QPWRQ1
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	1/45/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	1/3/0	-
CDM	ESD - CDM	750 V	1/3/0	1/3/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device TLC2264AQPWRQ1is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

### **Qualification Report**

### Approve Date 13-Sept-2021

#### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TLV2464CPWR	QBS Process Reference: CD3301RHHR	QBS Package Reference: TP S2042BD	QBS Package Reference: TPS2419DR
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device TLV2464CPWR is qualified at LEVEL1-260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Guainy and Environmental data is available at 11's external web site. <u>http://www.u</u> Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN ww admin team@list.ti.com

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